# **Product / Process Change Notification**



N° 2015-032-A

Dear Customer.

Please find attached our INFINEON Technologies PCN:

Introduction of AMKOR Philippines (ATP) as 2<sup>nd</sup> source assembly location and implementation of AMKOR's standard BOM affecting Infineon's TSSSOP28 packages.

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **30. June 2016**.
- Infineon aligns with the widely-recognized JEDEC STANDARD"JESD46", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG

Chairman of the Supervisory Board: Wolfgang Mayrhuber

Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Arunjai Mittal

Registered Office: Neubiberg

Commercial Register: München HRB 126492

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# Product / Process Change Notification



### N° 2015-032-A

▶ **Products affected:** Please refer to 1\_cip15032\_a attached

## **▶** Detailed Change Information:

Subject: Introduction of AMKOR Philippines (ATP) as 2nd source assembly

location and implementation of AMKOR's standard BOM affecting

Infineon's TSSSOP28 packages.

**Reason:** Implementation of a 2<sup>nd</sup> source to ensure long term supply.

Description:	<u>Old</u>	New
<ul><li>Assembly location</li></ul>	■ Infineon Malacca, Malaysia	Infineon Malacca, Malaysia <b>or</b> AMKOR, Philippines (ATP1)
<ul><li>Backside grinding location</li></ul>	<ul><li>Infineon Regensburg, Germany</li></ul>	Infineon Regensburg, Germany <b>or</b> AMKOR, Philippines (ATP1)
<ul> <li>Wire Diameter</li> <li>Mold compound</li> <li>Leadframe material/ plating</li> <li>Die attach material</li> </ul>	<ul><li>Infineon's assembly 'Bill-of- Material' (BoM)</li></ul>	■ AMKOR's assembly 'Bill-of- Material' (BoM)

▶ Product Identification: Traceability is ensured by

- Date code
- Package Marking (additional letter ,K' at AMKOR)
- Different Baunumber

► **ASSESSMENT:** Amkor Philippines (ATP1) is using state-of-the-art bill of material (BoM), has a long term experience as automotive assembler and is TS16949

has a long term experience as automotive assembler and is TS16949 certified and Infineon robust and green qualified.

There is no change in form, fit and function, quality or reliability.

The final test location will remain at Infineon (no change).

► Attachments: 1\_cip15032\_a affected product list

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### **▶** Time Schedule:

Final qualification report: Available on demand.

■ First samples available: Available on demand

■ Intended start of delivery: November 2016

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Introduction of AMKOR Philippines (ATP) as 2nd source assembly location and implementation of AMKOR's standard BOM affecting Infineon's TSSSOP28 packages.



Sales Name	SP number	OPN	Package
RX98-4	SP000743706	RX984XUMA1	PG-TSSOP-28-1
TDA5200	SP000016381	TDA5200XUMA1	PG-TSSOP-28-1
TDA5201	SP000012902	TDA5201XUMA1	PG-TSSOP-28-1
TDA5210	SP000016384	TDA5210XUMA1	PG-TSSOP-28-1
TDA5211	SP000016390	TDA5211XUMA1	PG-TSSOP-28-1
TDA5220	SP000014342	TDA5220XUMA1	PG-TSSOP-28-1
TDA5225	SP000507672	TDA5225XUMA1	PG-TSSOP-28-9
TDA5225C	SP001002316	TDA5225CXUMA1	PG-TSSOP-28-9
TDA5225HT	SP000857470	TDA5225HTXUMA1	PG-TSSOP-28-9
TDA5235	SP000507674	TDA5235XUMA1	PG-TSSOP-28-9
TDA5235HT	SP001098782	TDA5235HTXUMA1	PG-TSSOP-28-9
TDA5240	SP000550860	TDA5240XUMA1	PG-TSSOP-28-9
TDA7200	SP000296473	TDA7200XUMA1	PG-TSSOP-28-1
TDA7210	SP000524274	TDA7210XUMA1	PG-TSSOP-28-1